

ASSISTANT COMMISSIONER FOR PATENTS  
Washington, DC 20231

In re application of: Joohyeon PARK, et al.

Serial No.: 10/073,693

Filed: February 11, 2002

For: POLYMER FOR CHEMICALLY AMPLIFIED RESIST AND CHEMICALLY AMPLIFIED  
RESIST COMPOSITION CONTAINING THE SAME

Sir:

Transmitted herewith is a **Preliminary Amendment** in the above-identified application.

- [ ] Small entity status under 37 C.F.R. 1.9 and 1.27 has been previously established.  
[ ] Applicants assert small entity status under 37 C.F.R. 1.9 and 1.27.  
[x] No fee for additional claims is required.  
[ ] A filing fee for additional claims calculated as shown below, is required:

|   | (Col. 1)   | (Col. 2)   |         |
|---|------------|------------|---------|
| FOR:  | REMAINING  | HIGHEST    |         |
|   | AFTER      | PREVIOUSLY | PRESENT |
|   | AMENDMENT  | PAID FOR   | EXTRA   |
| TOTAL CLAIMS                                  | * Minus**  | =          | 0       |
| INDEP. CLAIMS                                 | * Minus*** | =          | 0       |
| [ ] FIRST PRESENTATION OF MULTIPLE DEP. CLAIM |            |            |         |

| SMALL ENTITY |     | OR | LARGE ENTITY |     |
|--------------|-----|----|--------------|-----|
| RATE         | FEE |    | RATE         | FEE |
| x \$ 9       | \$  |    | x \$ 18      | \$  |
| x \$ 42      | \$  |    | x \$ 84      | \$  |
| + \$ 140     | \$  |    | + \$ 280     | \$  |
| TOTAL: \$    |     | OR | TOTAL: \$    |     |

\* If the entry in Co. 1 is less than the entry in Col. 2, write "0" in Col. 3.

\*\* If the "Highest Number Previously Paid For" IN THIS SPACE is less than 20, write "20" in this space.

\*\*\* If the "Highest Number Previously Paid For" IN THIS SPACE is less than 3, write "3" in this space.

[ ] Also transmitted herewith are:

- [ ] Petition for extension under 37 C.F.R. 1.136 (in duplicate)  
[ ] Other:

[ ] Check(s) in the amount of \$0.00 is/are attached to cover:

- [ ] Filing fee for additional claims under 37 C.F.R. 1.16  
[ ] Petition fee for extension under 37 C.F.R. 1.136  
[ ] Other:

[X] The Assistant Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 50-0552.

- [X] Any filing fee under 37 C.F.R. 1.16 for the presentation of additional claims which are not paid by check submitted herewith.  
[X] Any patent application processing fees under 37 C.F.R. 1.17.  
[X] Any petition fees for extension under 37 C.F.R. 1.136 which are not paid by check submitted herewith, and it is hereby requested that this be a petition for an automatic extension of time under 37 CFR 1.136.

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I hereby certify that this correspondence and/or documents referred to as attached therein and/or fee are being deposited with the United States Postal Service as "first class mail" in an envelope addressed to "Assistant Commissioner for Patents, Washington, D.C. 20231" on

April 5, 2002.

DAVIDSON, DAVIDSON & KAPPEL, LLC

BY: *Rance J. Walker*

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TC 1/00



423.1036

**UNITED STATES PATENT AND TRADEMARK OFFICE**

Application of: Joohyeon PARK, et al. #40  
Serial No.: 10/073,693 NEAK  
Filed: February 11, 2002  
For: **POLYMER FOR CHEMICALLY AMPLIFIED  
RESIST AND CHEMICALLY AMPLIFIED RESIST  
COMPOSITION CONTAINING THE SAME**  
Examiner: TBD  
Art Unit: 1752

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**PRELIMINARY AMENDMENT**

Assistant Commissioner for Patents  
Washington, D.C. 20231

April 5, 2002

Sir:

Applicants request that the following Amendments be made in the above-identified matter before examination:

**IN THE SPECIFICATION:**

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On page 1, please replace the first and second paragraphs with the following:

a/ -- The present invention relates to a polymer with increased adhesion to substrate and a resist composition containing the same. More particularly, the present invention relates to a novel polymer that is useful for preparation of a photoresist suitable for fine works using various radiations, such as KrF or ArF excimer laser, X-rays such as synchrotron radiation, and charged particle rays such as electron beam, and a resist composition containing the polymer.

With an increase in the integration density of semiconductor devices, there is a demand